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TITLE: Method for manufacturing floor covering using waste urethane bumper

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ABSTRACTED-PUB-NO: KR2003079359A

BASIC-ABSTRACT:

NOVELTY - A method for manufacturing floor covering using waste urethane bumper is provided to recycle resources and conserve environment by recycling the waste urethane bumper as adhering material or floor covering material.

DETAILED DESCRIPTION - The method for manufacturing floor covering using waste urethane bumper comprises the steps of collecting the pulverized waste urethane bumper chips by shredding waste urethane bumper for automobiles into polyurethane chip having size of 1.5 mm or less; agitating the raw materials by physical mixing of 5 to 15 wt.% of the collected polyurethane chips with polyol and isocyanate at 60 deg.C; and injecting the agitated mixture into a mold for 2 to 4 minutes, and completely hardening the polyurethane form by demolding polyurethane form after a certain period of time, wherein the mixing process is performed at a temperature of 58 to 62 deg.C.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: METHOD MANUFACTURE FLOOR COVER WASTE URETHANE BUMPER

DERWENT-CLASS: A25 A32 A93

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